

What is claimed is:

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1. A substrate sawing process for a strip comprising:
a strip having a plurality of substrate areas, being cut on each of the substrate areas in the first phase by multi-alignment; and
the strip being cut on each of the substrate areas in the second phase by multi-alignment;
wherein the multi-alignment substantially consists of a plurality of alignments which are arranged around each of the substrate areas.
 2. The substrate sawing process, as defined in Claim 1, wherein the alignment is arranged around the encapsulated area of the substrate.
 3. The substrate sawing process, as defined in Claim 1, wherein the alignment substantially consists of at least three points.
 4. The substrate sawing process, as defined in Claim 1, wherein the strip further comprises a plurality of cutting marks around the substrate areas to define a plurality of cutting tracks in the first phase and the second phase.
 5. The substrate sawing process, as defined in Claim 1, wherein the first phase is at a right angle to the second phase in a parallel plane.
 6. The substrate sawing process, as defined in Claim 1, wherein at least two strips juxtapose on a plane, the strips having a plurality of substrate areas and being cut on each of the substrate areas in the first phase and the second phase by multi-alignment.